



Material Content Data Sheet



Sales Product Name		IPD60R385CP		Issued		20. July 2018		
MA#		MA000353932						
Package		PG-TO252-3-311		Weight*		316.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.064	1.60	1.60	16003	16003
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.21	45.27	452170	452759
wire	non noble metal	aluminium	7429-90-5	5.509	1.74	1.74	17408	17408
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.897	0.60		5995	
	plastics	brominated resin	-	2.033	0.64		6423	
	organic material	carbon black	1333-86-4	2.168	0.69		6852	
	plastics	epoxy resin	-	18.295	5.78		57810	
	inorganic material	silicondioxide	60676-86-0	111.125	35.11	42.82	351140	428220
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11966	11966
plating	non noble metal	nickel	7440-02-0	0.086	0.03		273	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	274
solder	noble metal	silver	7440-22-4	0.100	0.03		317	
	non noble metal	tin	7440-31-5	0.080	0.03		254	
	non noble metal	lead	7439-92-1	3.836	1.21	1.27	12122	12693
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.06	6.07	60598	60677
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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